

SMD metal oxide varistors

SMD varistors, Standard, 3225 series

Series/Type: VCRR3225*K***
Orderingcode:VCRR3225*K***

Date: January 2020
Version: 1

Features

- Improved component design in a compact case
- High surge current capability of up to 250A-1000A
- Superior performance at high temperature
- White package design without shadow in LED lighting application
- SMD mountable disk varistors, suitable for lead-free reflow / wave soldering

Applications

- Power supplies for telecommunication systems
- Protection for LED circuits
- Protection for consumer, industrial equipment
- Protection for automotive electronics

Type Code Designation

VCRR	3225	-	471	K
Logo	Size	Separate	Varistor voltage	J: ±5% K: ±10%
	2220(5750)		180=18V	
	3220(8050)		471=470V	
	3225(8060)		102=1000V	
	4032(1008)			

Internal Chip Size

Page Size	Chip Size	Page Size	Chip Size
2220	4*4mm	3225	5*5mm
3220	5*5mm	4032	7*7mm

General Technical Data

Parameter	Value	Unit
Operating temperature	-55 to +125	℃
Storage temperature	-55 to +150	℃
Electric strength	≥2.5	kV _{RMS}
Insulation resistance	≥100	MΩ

Electrical Characteristics

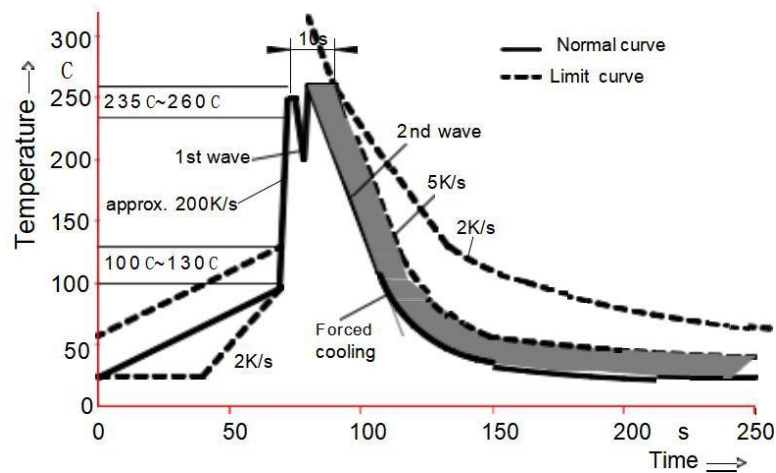
Part Number	Maximum Allowable Voltage		Varistor Voltage	Maximum Clamping Voltage		Withstanding Surge Current	Energy 10/1000 μ S		Rated Power	Typical Capacitance (Reference)
	AC (V)	DC (V)		IP(A)	VC(V)		(J) Standard	(J) High Surge		
Standard			V0.1mA(V)			I(A) Standard			(W)	@ 1 KHzPF
3225-180 K	11	14	18(15.3~20.7)	2.5	36	250	0.9	2.0	0.02	2800
3225-220 K	14	18	22(19.8~24.2)	2.5	43	250	1.1	2.4	0.02	2300
3225-270 K	17	22	27(24.3~29.7)	2.5	53	250	1.4	3.0	0.02	1800
3225-330K	20	26	33(29.7~36.3)	2.5	65	250	1.7	3.5	0.02	1500
3225-390 K	25	31	39(35.1~42.9)	2.5	77	250	2.1	4.0	0.02	1300
3225-470K	30	38	47(42.3~51.7)	2.5	93	250	2.5	5.0	0.02	1100
3225-560K	35	45	56(50.4~61.6)	2.5	110	250	3.1	6.0	0.02	890
3225-680K	40	56	68(61.2~74.8)	2.5	135	250	3.6	7.0	0.02	740
3225-820K	50	65	82(73.8~90.2)	10	135	1200	5.5	10	0.25	600
3225-101K	60	85	100(90~110)	10	165	1200	6.5	12	0.25	500
3225-121 K	75	100	120(108~132)	10	200	1200	7.8	12	0.25	420
3225-151K	95	125	150(135~165)	10	250	1200	9.7	13	0.25	330
3225-181K	115	150	180(162~198)	10	300	1200	11.7	16	0.25	280
3225-201K	130	170	200(185~225)	10	330	1200	13	17	0.25	250
3225-221K	140	180	220(198~242)	10	360	1200	14	19	0.25	230
3225-241K	150	200	240(216~264)	10	395	1200	15	21	0.25	210
3225-271K	175	225	270(243~297)	10	455	1200	18	24	0.25	185
3225-301K	190	250	300(270~330)	10	505	1200	20	26	0.25	165
3225-331K	210	275	330(297~363)	10	550	1200	23	28	0.25	150
3225-361K	230	300	360(324~396)	10	595	1200	25	32	0.25	140
3225-391K	250	320	390(351~429)	10	650	1200	25	35	0.25	130
3225-431K	275	350	430(387~473)	10	710	1200	28	40	0.25	110
3225-471K	300	385	470(423~517)	10	775	1200	30	42	0.25	105
3225-511K	320	415	510(459~561)	10	845	1200	30	45	0.25	100
3225-561K	350	460	560(504~616)	10	920	1200	30	49	0.25	90
3225-621K	385	505	620(558~682)	10	1025	1200	33	55	0.25	80
3225-681K	420	560	680(612~748)	10	1120	1200	33	60	0.25	75
3225-751K	460	615	750(675~825)	10	1240	1200	65	67	0.25	70
3225-781K	485	640	780(702~858)	10	1290	1200	65	67	0.25	70
3225-821K	510	670	820(738~902)	10	1355	1200	65	70	0.25	60

Soldering Guidelines

The usage of mild, non-activated fluxes for soldering is recommended, as well as proper cleaning of the PCB.

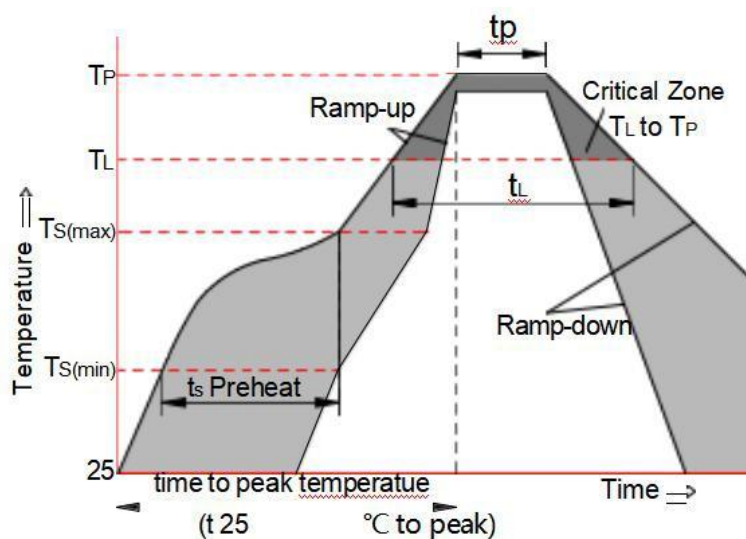
The components are suitable for reflow soldering per JEDEC J-STD-020C.

Wave Soldering



Temperature characteristics at component terminal with dual-wave soldering

Reflow Soldering



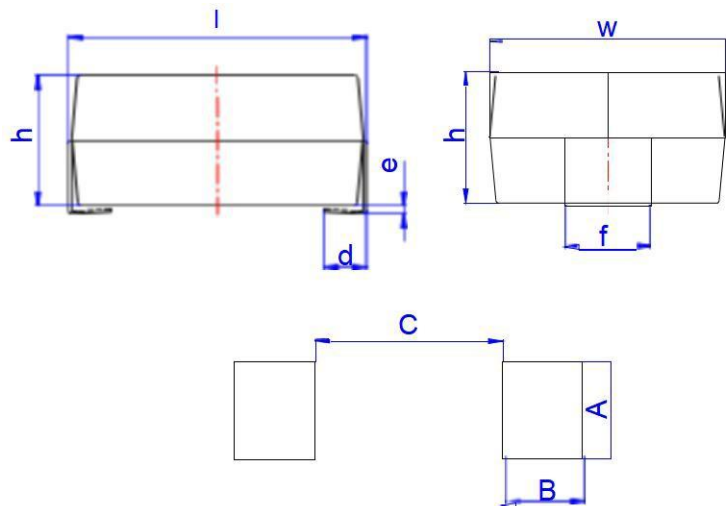
Profile feature		Sn-Pb assembly	Pb-Free assembly
Average ramp-up rate ($T_{S(max)}$ to T_p)		3 C/ sec. Max	3 C/ sec. Max
Preheat	-Temperature min. ($T_{S(min)}$)	+ 10 0 C	+ 15 0 C
	-Temperature max. ($T_{S(max)}$)	+ 15 0 C	+ 20 0 C
	-Time (t_{Smin} to t_{Smax})	60-120 secs.	60-180 secs.
$T_{S(max)}$ to T_L - Ramp-up Rate		3 C/ sec. Max	3 C/ sec. Max
Time maintained above	-Temperature min. (T_L)	+ 18 3 C	+ 21 7 C
	-Time (t_L)	60-150 secs.	60-150 secs.
Peak classification temperature (T_p)		+220 C to +240C	+240 C to +260C
Time within 5C of actual peak temperature (t_p)		10 secs. to 30 secs.	20 secs. to 40 secs.
Ramp-down rate		6 C/ sec. max.	6 C/ sec. max.
Time 25C to peak temperature		6 min. max.	8 min. max.

Notes: All temperature refer to topside of the package, measured on the package body surface
Maximum number of reflow cycles: 3

Storage Condition

- As far as possible, the components should be employed within 24 months after delivery from Kangtai Semiconductor.
- They should be left in their original packing to avoid soldering problems due to oxidized contacts.
- Storage temperature: - 25 up to + 45°C.
- Relative humidity: < 75 % annual average, < 95 % on max. 30 days in a year.

Dimensional Drawings

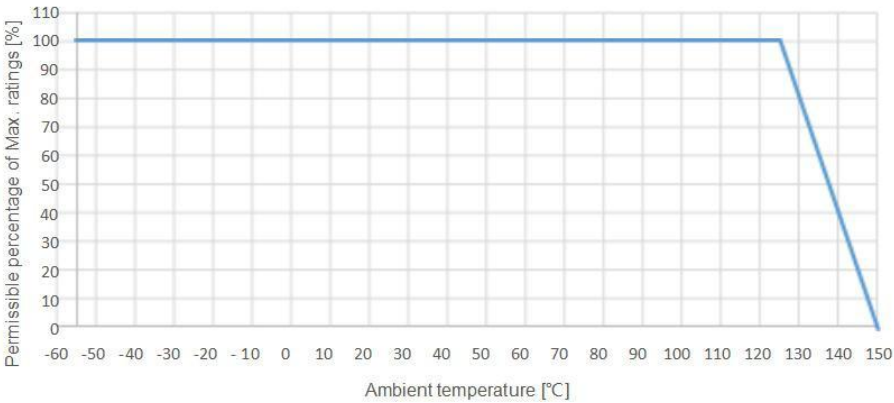


Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
l	7.7		8.3	0.303		0.327
w	6.0		6.6	0.236		0.260
h	3.3		4.0	0.122		0.150
d	1.2		1.8	0.047		0.071
e	0		0.3	0		0.012
f	2.70		3.3	0.106		0.130
A		3.5			0.138	
B		2.8			0.110	
C		4.5			0.177	

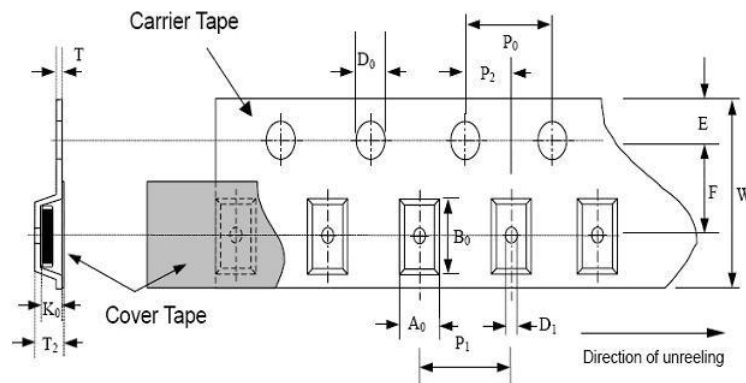
Recommended solder pad layout

Temperature Rating Curve

Max. current, energy, operating voltage and average power dissipation depending on ambient temperature

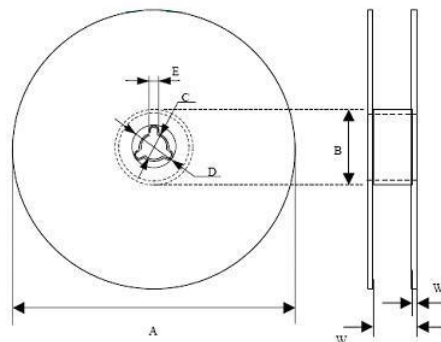


Packaging Specification



Type	A ₀ ±0.20	B ₀ ±0.20	K ₀ ±0.10	T max	T ₂ max	D ₀ +0.05	D ₁ ±0.05	P ₁ ±0.10	P ₂ ±0.05	P ₀ ±0.1	W ±0.30	E ±0.10	F ±0.05
3225	7.0	8.7	3.85	0.3	5.50	1.55	1.55	12.00	2.00	4.00	16.00	1.75	7.50
4032	8.4	10.8	3.85	0.3	5.50	1.55	1.55	12.00	2.00	4.00	24.00	1.75	11.50

Reel dimension



Type	A	B	C	D	E	W-W1	W ₁
3225	329.0±1.0	60.0±0.5	13.0±0.2	21.0±0.2	2.0±0.5	17.2±0.7	2.3±0.15

Quantity of taping packing(pcs) : 1000

